# 0.4 mm Pitch, 0.98 mm Mated Height, Board-to-Board / Board-to-FPC Connectors

## **DF37** Series



## Features

#### 1. Reduced size and board-occupied area

With the mated height of 0.98 mm, width of 2.98mm and length of 8.22 mm (30 positions) the connectors are one of the smallest in its class. Also 2.6mm depth short-lead type is available.

Sufficiently large flat areas allow pick-up with vacuum nozzles of automatic placement equipment.

#### 2. Reliable electrical and mechanical connection

Despite its small mated height, unique contact configuration, with a 2-point contacts and effective mating length of 0.25mm, assures highly reliable connection while confirming a complete mating with a definite tactile feel.

#### 3. Self alignment

Recognizing the difficulties of mating extremely small connectors in limited spaces, the connectors will self-align within 0.3mm.

### 4. Physical shock and vibration protection

2-point contact assures electrical connection in a shock or vibration applications.

#### 5. Solder wicking prevention

Nickel barriers (receptacles) and unique forming of the contacts (headers) prevent un-intentional solder wicking.

#### 6. Contamination protection

Insulator walls protect the contact areas against flux splatter or other physical particles contamination.

## **■**Further reduction of the board space.

## •Comparison of board mounting space







## ■Specifications

Ratings	Current rating	0.3 A	Operating temperature range	-35°C to +85°C (Note 1)	Storage temperature range	-10°C to +60°C (Note 2)
0	Voltage rating	30 V AC, DC	Operating humidity range	RH 20% to 80%	Storage humidity range	RH 40% to 70% (Note 2)

Item	Specification	Conditions
1.Insulation resistance	50 MΩ min	100 V DC
2.Withstanding voltage	No flashover or insulation breakdown	100 V AC / 1minute
3.Contact resistance	100 mΩ max.	20 mV AC, 1 kHz, 1 mA
4.Vibration	No electrical discontinuity of 1 $\mu$ s or longer No damage or parts dislocation	Frequency: 10 to 55 Hz, single amplitude of 0.75 mm, 2 hours, 3 axis
5.Humidity	Contact resistance: 100 m $\Omega$ max., Insulation resistance: 25 M $\Omega$ min.	96 hours at 40 $\pm 2^\circ C$ and humidity of 90 to 95% No damage or parts dislocation
6.Temperature cycle	Contact resistance: $100 \text{ m}\Omega \text{ max.}$ , Insulation resistance: $50 \text{ M}\Omega \text{ min.}$ No damage or parts dislocation	$-55^{\circ}$ C → 5 to $35^{\circ}$ C → $85^{\circ}$ C → 5 to $35^{\circ}$ C Time: 30 min. → 10 min. → 30 min. → 10 min. 5 cycles
7.Durability	Contact resistance: 100 mΩ max.	10 cycles
8.Resistance to	No deformation of components affecting	Reflow: At the recommended temperature profile
soldering heat	performance	Manual soldering: 350°C for 3 seconds

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" here refers to products stored for a long period prior to board mounting and use.

The operating temperature and humidity range covers the non-conducting condition of connectors after board mounting and the temporary storage conditions of transportation, etc.

### ■Materials

#### Receptacle

Part	Material	Finish	Remarks
Insulator	LCP	Color: Black	UL94V-0

#### Header

Part	Material	Finish	Remarks
Contacts	Phosphor bronze	Gold plated	

## Ordering Information

Receptacles	DF 37	# -	*	DS	-	0.4	V	(**)
	0	2	3	4		6	6	0
<ul> <li>Series name</li> </ul>	: DF37		4	Connec	tor s	style		
Configuration			1	DS: Red	epta	acle		
NB: With met	al fittings		6	Contact	pitc	h : 0.4	mm	
NC: Without r	netal fittings		6	Termina	l typ	be V: SI	MT v	ertical mount
SB: Short-lea	d type with meta	al fittings	7	Packagi	ng			
Number of co	ntacts			(51): En	nbos	sed tap	be pa	ckaging (8,000 pieces per reel)
NB/NC : 10, 16, 20	0, 24, 30, 34, 40, 50,	60, 70, 74		(53): En	nbos	sed tap	be pa	ckaging (1,000 pieces per reel)
SB : 10, 16, 20	), 24, 30, 34, 40, 50,	60						

Headers

## DF 37 # - \* DP - 0.4 V (\*\*)

	0	2	3	4	6	6	7		
<ol> <li>Series name</li> </ol>	: DF37		4	Connecto	or style				
Configuration			]	DP: Head	der				
B: With metal fi	ttings		6	Contact p	oitch : 0.4	1 mm			
C: Without meta	al fittings		6	Terminal	type V: S	SMT ver	tical mou	nt	
S Number of cont	acts		0	Packagin	g				
10, 16, 20, 24, 30	0, 34, 40, 50, 6	60, 70, 74	(	(51): Eml	possed ta	ape pacl	kaging (8	,000 pieces p	per reel)
			(	(53): Eml	oossed ta	ape pacl	kaging (1	,000 pieces p	per reel)
Note · The short-lea	ad type is on	lv availab	le for	the rece	ptacle s	de (with	hardwar	re)	





## Recommended metal mask dimensions



## ■Recommended PCB mounting pattern



#### With metal fittings

	0							
	Part Number	CL No.	Number of Contacts	А	В	С	D	E
	DF37SB-10DS-0.4V(51)	CL684-3500-2-51	10	4.22	1.6	0.8	3.7	4.46
	DF37SB-16DS-0.4V(51)	CL684-3501-5-51	16	5.42	2.8	1.2	4.9	5.66
	DF37SB-20DS-0.4V(51)	CL684-3502-8-51	20	6.22	3.6	1.6	5.7	6.46
$\star$	DF37SB-24DS-0.4V(51)	CL684-3503-0-51	24	7.02	4.4	2	6.5	7.26
$\star$	DF37SB-30DS-0.4V(51)	CL684-3504-3-51	30	8.22	5.6	2	7.7	8.46
	DF37SB-34DS-0.4V(51)	CL684-3505-6-51	34	9.02	6.4	2.4	8.5	9.26
	DF37SB-40DS-0.4V(51)	CL684-3506-9-51	40	10.22	7.6	2.4	9.7	10.46
	DF37SB-50DS-0.4V(51)	CL684-3507-1-51	50	12.22	9.6	2.8	11.7	12.46
	DF37SB-60DS-0.4V(51)	CL684-3508-4-51	60	14.22	11.6	3.2	13.7	14.46

Note 1: Tape and reel packaging (8,000 pieces/reel). Order by number of reels.

Note 2: This connector is NOT polarized.

★ Indicates "available". No marking "under development".

#### All dimensions: mm

# 4 **HS**



Recommended metal mask dimensions



■Recommended PCB mounting pattern



•With metal fittings





All dimensions: mm

Part Number	CL No.	Number of Contacts	А	В	С	D	Е
DF37B-10DP-0.4V(51)	CL684-3037-0-51	10	3.14	1.6	0.8	2.62	3.38
DF37B-16DP-0.4V(51)	CL684-3057-7-51	16	4.34	2.8	1.2	3.82	4.58
DF37B-20DP-0.4V(51)	CL684-3008-1-51	20	5.17	3.6	1.6	4.62	5.38
DF37B-24DP-0.4V(51)	CL684-3009-4-51	24	5.94	4.4	2	5.42	6.18
DF37B-30DP-0.4V(51)	CL684-3010-3-51	30	7.14	5.6	2	6.62	7.38
DF37B-34DP-0.4V(51)	CL684-3064-2-51	34	7.94	6.4	2.4	7.42	8.18
DF37B-40DP-0.4V(51)	CL684-3011-6-51	40	9.14	7.6	2.4	8.62	9.38
DF37B-50DP-0.4V(51)	CL684-3012-9-51	50	11.14	9.6	2.8	10.62	11.38
DF37B-60DP-0.4V(51)	CL684-3013-1-51	60	13.14	11.6	3.2	12.62	13.38
DF37B-70DP-0.4V(51)	CL684-3014-4-51	70	15.14	13.6	3.6	14.62	15.38
DF37B-74DP-0.4V(51)	CL684-3071-8-51	74	15.94	14.4	4	15.42	16.18

#### •Without metal fittings

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Part Number	CL No.	Number of Contacts	А	В	С
DF37C-10DP-0.4V(51)	CL684-3039-5-51	10	3.14	1.6	0.8
DF37C-16DP-0.4V(51)	CL684-3058-0-51	16	4.34	2.8	1.2
DF37C-20DP-0.4V(51)	CL684-3024-8-51	20	5.17	3.6	1.6
DF37C-24DP-0.4V(51)	CL684-3025-0-51	24	5.94	4.4	2
DF37C-30DP-0.4V(51)	CL684-3026-3-51	30	7.14	5.6	2
DF37C-34DP-0.4V(51)	CL684-3085-2-51	34	7.94	6.4	2.4
DF37C-40DP-0.4V(51)	CL684-3027-6-51	40	9.14	7.6	2.4
DF37C-50DP-0.4V(51)	CL684-3028-9-51	50	11.14	9.6	2.8
DF37C-60DP-0.4V(51)	CL684-3029-1-51	60	13.14	11.6	3.2
DF37C-70DP-0.4V(51)	CL684-3030-0-51	70	15.14	13.6	3.6
DF37C-74DP-0.4V(51)	CL684-3073-3-51	74	15.94	14.4	4

Note 1: Tape and reel packaging (8,000 pieces/reel). Order by number of reels. Note 2: This connector is NOT polarized.

#### All dimensions: mm

# Embossed Carrier Tape Dimensions

#### Receptacle (less than 70 positions)





### Reel Dimensions





		<i>_</i>		10113. 11111
Part Number	A	В	С	D
DF37#-10DS-0.4V(51)	7.5	16	17.5	21.5
DF37#-16DS-0.4V(51)	7.5	16	17.5	21.5
DF37#-20DS-0.4V(51)	7.5	16	17.5	21.5
DF37#-24DS-0.4V(51)	7.5	16	17.5	21.5
DF37#-30DS-0.4V(51)	11.5	24	25.5	29.5
DF37#-34DS-0.4V(51)	11.5	24	25.5	29.5
DF37#-40DS-0.4V(51)	11.5	24	25.5	29.5
DF37#-50DS-0.4V(51)	11.5	24	25.5	29.5
DF37#-60DS-0.4V(51)	11.5	24	25.5	29.5
DF37#-70DS-0.4V(51)	14.2	32	33.5	37.5
DF37#-74DS-0.4V(51)	14.2	32	33.5	37.5
#: NB or NC, SB				

Tape and reel packaging (8,000 pieces/reel).

#### All dimensions: mm

# Embossed Carrier Tape Dimensions

## •Header (less than 74 positions)



#### •Header (74 positions and above)



#### Reel Dimensions





#### All dimensions: mm

Part Number	Α	В	С	D
DF37#-10DP-0.4V(51)	5.5	12	13.5	17.5
DF37#-16DP-0.4V(51)	7.5	16	17.5	21.5
DF37#-20DP-0.4V(51)	7.5	16	17.5	21.5
DF37#-24DP-0.4V(51)	7.5	16	17.5	21.5
DF37#-30DP-0.4V(51)	11.5	24	25.5	29.5
DF37#-34DP-0.4V(51)	11.5	24	25.5	29.5
DF37#-40DP-0.4V(51)	11.5	24	25.5	29.5
DF37#-50DP-0.4V(51)	11.5	24	25.5	29.5
DF37#-60DP-0.4V(51)	11.5	24	25.5	29.5
DF37#-70DP-0.4V(51)	11.5	24	25.5	29.5
DF37#-74DP-0.4V(51)	14.2	32	33.5	37.5
#: NB or NC, SB				

Tape and reel packaging (8,000 pieces/reel).

## ■Usage Recommendations

1.Recommended temperature profile	
	Temperature (°C)
	250 °C
	220°C/
	200 - 60sec max
	180°C
	150 - 150°C - 7
	100 90~120sec
	50 -
	Room temperature
	0 50 100 150 200 250 300
	Time (sec.)
	<ul> <li>Note 1: Up to 2 cycles of Reflow soldering are possible under the same conditions, provided that there is a return to normal temperature between the first and second cycle.</li> <li>Note 2: The temperature profile indicates the board surface temperature at the point of contacts with the connector</li> </ul>
	terminals.
2.Recommended manual soldering	
2.Recommended manual soldering 3.Recommended screen thickness and open	terminals. Manual soldering: 340±10℃ for 3 seconds Thickness: 0.12 mm
<ul><li>2.Recommended manual soldering</li><li>3.Recommended screen thickness and open area ratio (Pattern area ratio)</li></ul>	Manual soldering: 340±10℃ for 3 seconds
3.Recommended screen thickness and open	Manual soldering: 340±10°C for 3 seconds Thickness: 0.12 mm
3.Recommended screen thickness and open area ratio (Pattern area ratio)	Manual soldering: 340±10°C for 3 seconds Thickness: 0.12 mm Open area ratio: Receptacle:80%(NB/NC), Plug: 70%
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## ■Handling Precautions when Mating Connectors



## ■Handling Precautions When Un-mating Connectors

Fully mated
Lift even, keeping both connectors parallel to each other
<ul><li>When handling, circumstances may prevent the connectors from being kept parallel when un-mating. One end may be lifted as shown.</li><li>However, to use this procedure the connector must be mounted on sufficiently rigid circuit board.</li><li>Any deflection of the board during this opera- tion may result in damage to the connector or solder joints.</li></ul>
Do not attempt to start the un-mating of the connectors from one side or corner. Failure to exercise caution when un-mating the connectors mounted on the non-rigid FPC may also result in connector breakage. It is the responsibility of the user to perform verification of the repeated mating / un-mating cycles with the connectors mounted on the applicable FPC.
When the rigidity of the FPC is low, there is a risk that the connector could break as illustrat- ed in the diagram at left. Please use the connectors after performing a check of repeated operation with the FPC that the customer will be using. Evaluative results of FPC rigidity and various items are available. Please inquire.